

### SPREAD SPECTRUM CLOCK SYNTHESIZER

### ICS650-44

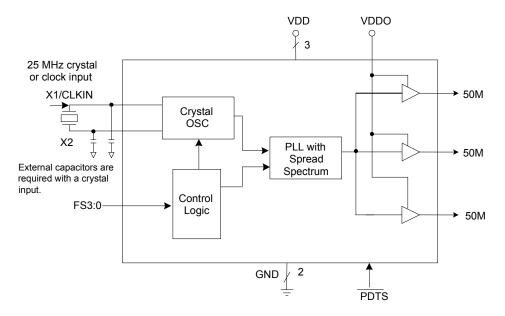
# **Description**

The ICS650-44 is a spread spectrum clock synthesizer intended for video projector and digital TV applications. It generates three copies of an EMI optimized 50 MHz clock signal (EMI peak reduction of 7 to 14 dB on 3rd through 19th harmonics) through the use of Spread Spectrum techniques from a 25 MHz crystal or clock input. The modulation rate is 50 kHz.

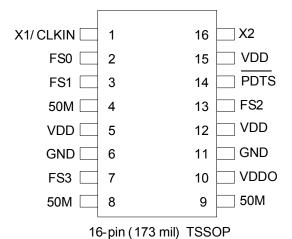
### **Features**

- Packaged in 16-pin TSSOP (173 mil)
- Supply voltages: VDD = 3.3 V, VDDO = 2.5 V
- Peak-to-peak jitter: ±125 ps typ
- Output duty cycle 45/55% (worst case)
- 25 MHz crystal or reference clock input
- Zero (0) ppm frequency error on all output clocks
- Advanced, low-power CMOS process
- Industrial temperature range (-40 to +85°C)
- · Pb (lead) free package

### **Block Diagram**



# **Pin Assignment**



**Spread Spectrum and Output Configuration Table** 

FS3	FS2	FS1	FS0	Spread Type	SS Out
0	0	0	0	Center	±0.25
0	0	0	1	Center	±0.50
0	0	1	0	Center	±0.75
0	0	1	1	Center	±1.00
0	1	0	0	Center	±1.25
0	1	0	1	Center	±1.50
0	1	1	0	Center	±1.75
0	1	1	1	Center	±2.00
1	0	0	0	Down	-0.5
1	0	0	1	Down	-0.75
1	0	1	0	Down	-1.0
1	0	1	1	Down	-1.25
1	1	0	0	Down	-1.5
1	1	0	1	Down	-1.75
1	1	1	0	Down	-2.0
1	1	1	1	Off	Off

### **Pin Descriptions**

Pin Number	Pin Name	Pin Type	Pin Description
1	X1/CLKIN	Input	Crystal input. Connect this pin to a 25 MHz crystal or external input clock.
2	FS0	Input	Select pin 0. Internal pull-up resistor. See table on page 2.
3	FS1	Input	Select pin 1. Internal pull-up resistor. See table on page 2.
4	50M	Output	Spread Spectrum output. Weak internal pull-down when tri-stated.
5	VDD	Power	Connect to +3.3 V.
6	GND	Power	Connect to ground.
7	FS3	Input	Select pin 3. Internal pull-up resistor. See table on page 2.
8	50M	Output	Spread Spectrum output. Weak internal pull-down when tri-stated.
9	50M	Output	Spread Spectrum output. Weak internal pull-down when tri-stated.
10	VDDO	Power	Connect to +2.5 V.
11	GND	Power	Connect to ground.
12	VDD	Power	Connect to +3.3 V.
13	FS2	Input	Select pin 2. Internal pull-up resistor. See table on page 2.
14	PDTS	Input	Powers down entire chip. Tri-states CLK outputs when low. Internal pull-up.
15	VDD	Power	Connect to +3.3 V.
16	X2	Output	Crystal Output. Connect this pin to a 25 MHz crystal. Do not connect if clock input is used.

## **External Components**

### **Decoupling Capacitor**

As with any high-performance mixed-signal IC, the ICS650-44 must be isolated from system power supply noise to perform optimally.

A decoupling capacitor of 0.01µF must be connected between each VDD and the PCB ground plane.

### **Series Termination Resistor**

Clock output traces over one inch should use series termination. To series terminate a  $50\Omega\,\text{trace}$  (a commonly used trace impedance), place a  $33\Omega\,\text{resistor}$  in series with the clock line, as close to the clock output pin as possible. The nominal impedance of the clock output is  $20\Omega$ 

### **Crystal Load Capacitors**

The device crystal connections should include pads for

small capacitors from X1 to ground and from X2 to ground. These capacitors are used to adjust the stray capacitance of the board to match the nominally required crystal load capacitance. Because load capacitance can only be increased in this trimming process, it is important to keep stray capacitance to a minimum by using very short PCB traces (and no vias) between the crystal and device. Crystal capacitors must be connected from each of the pins X1 and X2 to ground.

The value (in pF) of these crystal caps should equal ( $C_L$  -6 pF)\*2. In this equation,  $C_L$ = crystal load capacitance in pF. Example: For a crystal with a 16 pF load capacitance, each crystal capacitor would be 20 pF [(16-6) x 2] = 20.

### **PCB Layout Recommendations**

For optimum device performance and lowest output phase noise, the following guidelines should be observed.

- 1) The  $0.01\mu F$  decoupling capacitors should be mounted on the component side of the board as close to the VDD pin as possible. No vias should be used between the decoupling capacitors and VDD pins. The PCB trace to VDD pins should be kept as short as possible, as should the PCB trace to the ground via.
- 2) The external crystal should be mounted just next to the device with short traces. The X1 and X2 traces should not be routed next to each other with minimum spaces, instead they should be separated and away from other traces.
- 3) To minimize EMI, the  $33\Omega$  series termination resistor should be placed close to the clock output.
- 4) An optimum layout is one with all components on the same side of the board, minimizing vias through other signal layers. Other signal traces should be routed away from the ICS650-44. This includes signal traces just underneath the device, or on layers adjacent to the ground plane layer used by the device.

## **Absolute Maximum Ratings**

Stresses above the ratings listed below can cause permanent damage to the ICS650-44. These ratings, which are standard values for IDT commercially rated parts, are stress ratings only. Functional operation of the device at these or any other conditions above those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods can affect product reliability. Electrical parameters are guaranteed only over the recommended operating temperature range.

Item	Rating
Supply Voltage, VDD	5 V
All Inputs and Outputs	-0.5 V to VDD+0.5 V
Ambient Operating Temperature	-40 to +85° C
Storage Temperature	-65 to +150° C
Junction Temperature	125° C
Soldering Temperature (max. of 10 seconds)	260° C

# **Recommended Operation Conditions**

Parameter	Min.	Тур.	Max.	Units
Ambient Operating Temperature	-40	_	+85	°C
Power Supply Voltage (VDD, with respect to GND)	+3.135	+3.3	+3.465	V
Power Supply Voltage (VDDO)	+2.375	+2.5	+2.625	V
Power Supply Ramp Time, Figure 4			4	ms

### **DC Electrical Characteristics**

Unless stated otherwise, VDD = 3.3 V  $\pm$ 5%, VDDO = 2.5 V  $\pm$ 5%, Ambient Temperature -40 to +85° C

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Units
	IDD	no load		27		mA
Operating Supply Current		PDTS = 0, no load		40		uA
Operating Supply Surrent		no load		4		mA
	IDDO	PDTS = 0, no load		1		uA
Input High Voltage	V <sub>IH</sub>	FS3:0, PDTS	2			V
Input Low Voltage	V <sub>IL</sub>	FS3:0, PDTS			0.8	V
Input High Voltage	V <sub>IH</sub>	X1/CLKIN	0.7 x VDD			V
Input Low Voltage	V <sub>IL</sub>	X1/CLKIN			0.3 x VDD	V
Output High Voltage	V <sub>OH</sub>	I <sub>OH</sub> = -4 mA	1.8			V
Output Low Voltage	V <sub>OL</sub>	I <sub>OL</sub> = 4 mA			0.6	V
Short Circuit Current	Ios			±50		mA
Nominal Output Impedance	Z <sub>O</sub>			20		Ω
Internal Pull-up Resistor	R <sub>PU</sub>	FS3:0, PDTS		360		kΩ
Input Leakage Current	l <sub>l</sub>	FS3:0, PDTS, VIN=VDD		1		uA
Internal Pull-down Resistor	R <sub>PD</sub>	CLK outputs		900		kΩ
Input Capacitance	C <sub>IN</sub>	Inputs		4		pF

### **AC Electrical Characteristics**

Unless stated otherwise, VDD = 3.3 V ±5%, VDDO = 2.5 V ±5%, Ambient Temperature -40 to +85° C

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Units
Input Frequency	F <sub>IN</sub>	Crystal or clock input		25		MHz
Spread Spectrum Modulation Frequency				50		kHz
Duty Cycle	t <sub>2</sub> /t <sub>1</sub>	At VDD/2, Note 1 and Figures 1 and 2	45	50	55	%
Output Fall Time	t <sub>3</sub>	80% to 20%, Note 1 and Figures 1 & 3		1.5		ns
Output Rise Time	t <sub>4</sub>	20% to 80%, Note 1 and Figures 1 & 3		1.5		ns
One Sigma Clock Period Jitter		Note 1		30		ps
Absolute Jitter, Peak-to-Peak	t <sub>ja</sub>	Deviation from mean, Note1 & Figures 1 and 6		±125		ps
Output Enable Time	t <sub>EN</sub>	PDTS high to PLL locked to within 1% of final value, Figure 5		2.5	5	ms
Output Disable Time	t <sub>DIS</sub>	PDTS low to tri-state, Figure 5		20		ns
Output-to-Output Skew				±180		ps
Power-up Time	t <sub>P</sub>	PLL lock-time from power-up to 1% of final value, Figure 4		6	10	ms

Note 1: Measured with 5 pF load.

# **Timing Diagrams**

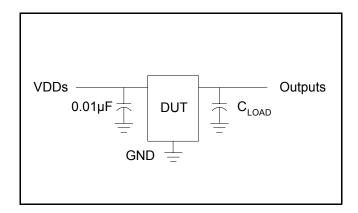


Figure 1: Test and Measurement Setup

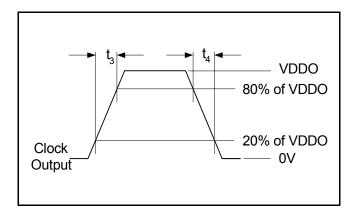


Figure 3: Rise and Fall Time Definitions

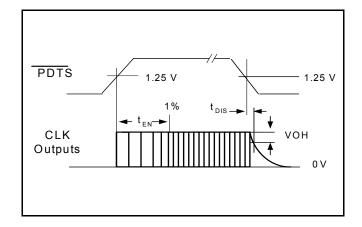
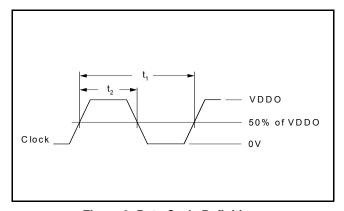


Figure 5: PDTS to Stable Clock Output Timing



**Figure 2: Duty Cycle Definitions** 

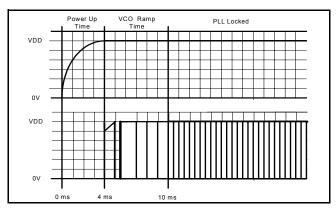
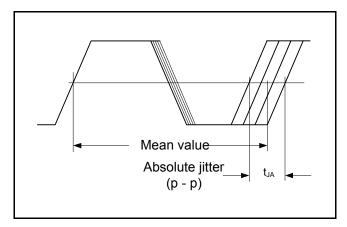


Figure 4: Power Up and PLL Lock Timing

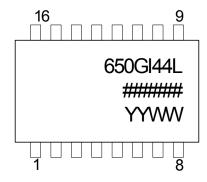


**Figure 6: Short Term Jitter Definition** 

### **Thermal Characteristics**

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Units
Thermal Resistance Junction to	$\theta_{JA}$	Still air		78		° C/W
Ambient	$\theta_{JA}$	1 m/s air flow		70		° C/W
	$\theta_{JA}$	3 m/s air flow		68		° C/W
Thermal Resistance Junction to Case	$\theta_{JC}$			37		° C/W

# **Marking Diagram (Pb free)**

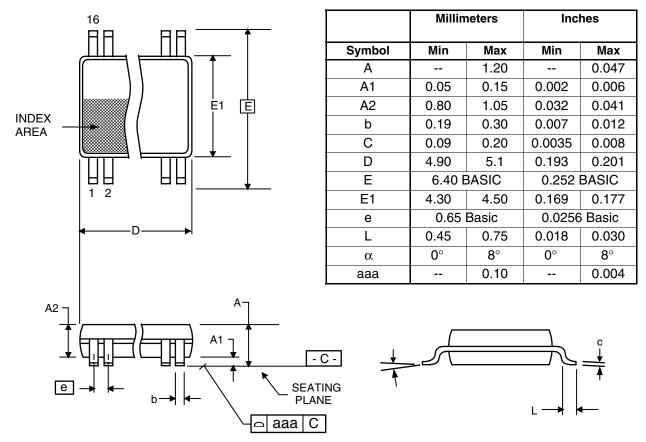


### Notes:

- 1. ###### is the lot number.
- 2. YYWW is the last two digits of the year and the week number that the part was assembled.
- 3. "I" designates industrial temperature range.
- 4. "L" designates Pb (lead) free package.
- 5. Bottom marking: (origin)
  Origin = country of origin of not USA.

### Package Outline and Package Dimensions (16-pin TSSOP, 173 Mil. Narrow Body)

Package dimensions are kept current with JEDEC Publication No. 95



# **Ordering Information**

Part / Order Number	Marking	Shipping Packaging	Package	Temperature
650GI-44LF	see page 7	Tubes	16-pin TSSOP	-40 to +85° C
650GI-44LFT		Tape and Reel	16-pin TSSOP	-40 to +85° C

#### Parts that are ordered with a "LF" suffix to the part number are the Pb-Free configuration and are RoHS compliant.

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# **Revision History**

Rev.	Originator	Date	Description of Change
-	P. Griffith	05/13/05	New proposal.
Α	P. Griffith	05/24/05	Move from Advance (proposal) to Preliminary. Added ICS part number and LF.
В	P. Griffith	06/14/05	Added "Output-to-Output skew" psec of ±180 ps.
С	P. Griffith	08/03/05	Removed references to SS_EN.
D		10/27/09	Added EOL note for non-green parts
Е		05/13/10	Removed EOL note and non-green parts

ICS650-44 SPREAD SPECTRUM CLOCK SYNTHESIZER

**CLOCK SYNTHESIZER** 

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(Rev.1.0 Mar 2020)

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